



Product Change Notification

CN-202402020F

Issue date: 08 May 2024

Effective date: 20 Aug 2024

Here's your personalized quality information concerning products our customers and partners purchased from Nexperia.

For more details please contact your respective Nexperia CSR/AM.



Release of Cu wire for SOD123F

Change
Category

☐ Wafer Fab Process	☐ Assembly Process	☐ Product Marking	☐ Test Location	☐ Design
☐ Wafer Fab Material	☒ Assembly Material	☐ Mechanical Specification	☐ Test Process	☐ Errata
☐ Wafer Fab Location	☐ Assembly Location	☐ Packing/Shipping/Labeling	☐ Test Equipment	☐ Electrical spec./Test coverage

Details of this change

Scheduled changes affect product types in SOD123F package only. The bond wire material will be changed from gold (Au) to copper (Cu). New mold compound materials will be introduced. Gold wire remains qualified for supply security reasons only.

Old product: Wire material is Au (with currently used mold compound)
Changed product: Wire material is Cu (with new mold compound material)

Reliability qualification and full electrical characterization over temperature have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

PCN-FORM-Rev_5_0_2-CN-202402020F.xlsm:

https://qcm.nexperia.com/Document/DOC-573038/PCN-FORM-Rev_5_0_2-CN-202402020F.xlsm

PCN-Delta-Qualification-Matrix-ZVEI-5_0_16-CN-202402020F.xlsm:

https://qcm.nexperia.com/Document/DOC-573023/PCN-Delta-Qualification-Matrix-ZVEI-5_0_16-CN-202402020F.xlsm

SelfQualificationReportCN-202402020F.pdf:

<https://qcm.nexperia.com/Document/DOC-573022/SelfQualificationReportCN-202402020F.pdf>

Why do we implement this change?

Aligning with world technology standards, Nexperia continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.

Identification of affected products

Changed products can be identified by date code after implementation.

Management summary

SOD123F Introduction of copper wire and new assembly materials

Product availability

Production

Planned first shipment: 19 Aug 2024

Existing inventory will be shipped until depleted

Sample information

Samples are available upon request

Impact

No impact to the product's functionality anticipated

Data sheet revision

No impact to existing datasheet

Feedback

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 07 Jun 2024. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Additional information

[View Change Notification Online](#)

Contact and support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support Team.

For specific questions on this notice or the products affected please contact our specialist directly: pcn@nexperia.com

In case of distribution, please contact you distribution partner.

About Nexperia B.V.

We at Nexperia are the efficiency semiconductor company. We deliver over 90 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.

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